

REISSUE APPLICATION DECLARATION BY THE INVENTOR

Docket Number (Optional)

FI-9-97-207 US2

I hereby declare that:

Each inventor's residence, mailing address and citizenship are stated below next to their name.

I believe the inventors named below to be the original and first inventor(s) of the subject matter which is described and claimed in patent number 6,297,140, granted October 2, 2001, and for which a reissue patent is sought on the invention entitled

METHOD TO PLATE C4 TO COPPER STUD

the specification of which

☒ is attached hereto.

☐ was filed on _____ as reissue application number _____
and was amended on _____
(if applicable)

I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.

☐ I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or (f), or 365(b). Attached is form PTO/SB/2B (or equivalent) listing the foreign applications.

I verily believe the original patent to be wholly or partly inoperative or invalid, for the reasons described below. (Check all boxes that apply.)

☐ by reason of a defective specification or drawing.

☒ by reason of the patentee claiming more or less than he had the right to claim in the patent.

☐ by reason of other errors.

At least one error upon which reissue is based is described below. If the reissue is a broadening reissue, such must be stated with an explanation as to the nature of the broadening:

The patentee claimed less than he had the right to claim in not including claims along the lines of newly-presented claims 24-43. This is a broadened reissue. The broadening is directed to not reciting "depositing a photoresist layer over said plating seed layer" and "remaining portions of said photoresist layer" and "removing photoresist remaining in said at least one recess" contained in Claim 1 and claims dependent therein or not reciting "providing a pad in said at least one recess for preventing removal of portions of said seed layer in said at least one recess" and "removing said pad" included in Claim 22 and claims dependent thereon. Not requiring the above features is supported by the original patent. For instance, although these features relate to referred aspects of the invention in order to assure the preventing of dishing of the seed layer in the depression, they are not mandatory. In particular, the disclosure at column 6, lines 3-4 and 42-44 disclose the optional nature of these embodiments.

For instance, column 6, lines 3-4 state:

"After formation of the seed layer, a photoresist may be deposited over the seed layer."

(cont'd on page 2)

(cont'd from page 1)

Column 6, lines 42-44 state:

"According to an alternative embodiment, photoresist may not be utilized. Since an embodiment may utilize a very hard pad to prevent dishing of the seed layer in the depression."

The use of the term "may" with the above statements is a clear appreciation and recognition that the method is being practiced without employing these steps. This is further supported by column 6, line 53 that states

"After removal of the resist, if necessary . . ."

The patentee also claimed less than he had the right to claim in not including claims 44-62 that ultimately depend from claim 22. These claims generally correspond to claim 2-12 and 14-21 respectively except that they ultimately depend upon claim 22 rather than ultimately from Claim 1. Claim 54 further differs from Claim 12 in not reciting the "photoresist layer."

Claims 1, 16, 20, 22 and 23 have also been amended by deleting the phrase "the steps of" or "the step of" which seems superfluous.

(REISSUE APPLICATION DECLARATION BY THE INVENTOR, page 3)

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All errors corrected in this reissue application arose without any deceptive intention on the part of the applicant. As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the United States Patent and Trademark Office connected therewith.

Name(s)	Registration Number	Name(s)	Registration Number

Correspondence Address: Direct all communications about the application to:

☐ Customer Number

Customer Number

OR

☒ Firm or Individual Name

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20036

Country

Telephone
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202-293-6229

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine and imprisonment, or both, under 18 U.S.C. 1001, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this declaration is directed.

Full name of sole or first inventor (given name, family name)

Cyprian Emeka Uzoh

Inventor's signature *Cyprian Emeka Uzoh*

Date 9/20/03

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Full name of second joint inventor (given name, family name)

Daniel C. Edelstein

Inventor's signature

Date

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Mailing Address

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Full name of third joint inventor (given name, family name)

Inventor's signature

Date

Residence

Citizenship

Mailing Address

☐ Additional joint inventors or legal representative(s) are named on separately numbered sheets forms PTO/SB/02A or 02LR attached hereto.

PTO/SB/51 (08-03)

Approved for use through 01/31/2004. OMB 0651-0033

U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

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Name(s)	Registration Number	Name(s)	Registration Number
<p>Correspondence Address: Direct all communications about the application to:</p> <p><input type="checkbox"/> Customer Number Customer Number</p> <p>OR</p>			
<p><input checked="" type="checkbox"/> Firm or Individual Name Burton A. Amernick</p>			
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City Washington		State DC	
Country		Zip 20036	
		Telephone 202-331-7111	
		Fax 202-293-6229	
<p>I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine and imprisonment, or both, under 18 U.S.C. 1001, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this declaration is directed.</p>			
<p>Full name of sole or first inventor (given name, family name) Cyprian Emeka Uzoh</p>			
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Mailing Address			
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Inventor's signature 		Date 9/29/03	
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Mailing Address 15 Charlotte Street, White Plains, New York 10606			
<p>Full name of third joint inventor (given name, family name)</p>			
Inventor's signature		Date	
Residence		Citizenship	
Mailing Address			
<p><input type="checkbox"/> Additional joint inventors or legal representative(s) are named on separately numbered sheets forms PTO/SB/02A or 02LR attached hereto.</p>			